

## **DuPont™ CuSolve™**

Copper Compatible Removers

Optimized to Selectively Remove Post-Etch Residues

#### **Product Description**

DuPont™ CuSolve™ copper compatible removers are designed to remove post-etch residue. They perform well in a variety of equipment including single-wafer and batch spray platforms.

### **Features**

- Formulated for optimum compatibility with copper substrates
- Compatible with single-wafer type clean equipment
- Compatible with batch spray type clean equipment
- Aqueous-based formulation
- No post-clean rinse required other than water
- Operates well below the flashpoint of the solution
- · Low evaporation rate at operating temperature
- Low viscosity
- High flashpoint
- No banned or reportable chemical components
- Copper oxide removal time <30 seconds at 25 °C
- Compatible with a variety of Low-k films
- Bathlife >48 hours
- Lower cost of ownership than competitive products

#### **Benefits**

- Improved yields in copper processing
- Offers flexibility in equipment choice
- Greater device reliability and product yields
- Helps reduce environmental, health and safety concerns
- Provides a safer chemical process
- Long bath life, low air emissions, low factory operating cost
- Ease of operation of tool and chemical supply equipment

Figure 1. Before Clean

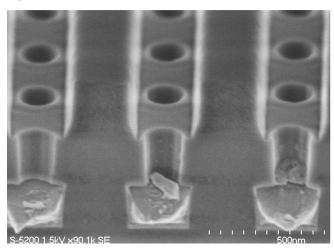


Figure 2. After Clean with DuPont™ CuSolve™ Copper Compatible Remover

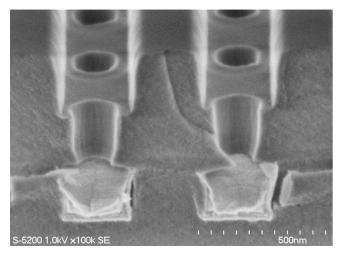
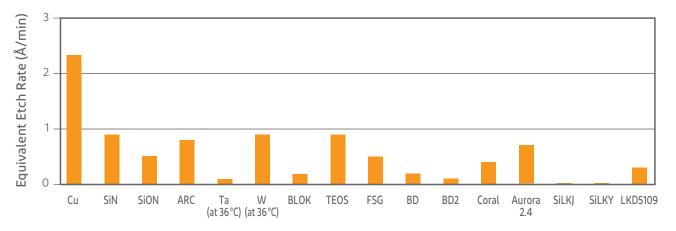


Figure 3. Materials Compatibility (total loss in 10 minutes at 25 °C)



Substrates were exposed to DuPont™ CuSolve™ EKC520™ at 25 °C for 10 minutes. Etch rates were calculated.



ekctech.dupont.com

# For more information on DuPont™ CuSolve™ or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

DuPont", the DuPont Oval Logo, and all products, unless otherwise noted, denoted with TM, SM or ® are trademarks, service marks or registered trademarks of affiliates of DuPont de Nemours, Inc. © 2019 DuPont de Nemours, Inc. All rights reserved.

K-10751-2 (05/19)